Registration Information: https://www.ieee-itherm.net/itherm/conference/registration

19th Intersociety Conference on Thermal and Thermomechanical Phenomena in Electronic Systems

ITherm is the leading international conference for scientific and engineering exploration of thermal, thermomechanical and emerging technology issues associated with electronic devices, packages, and systems. Sponsored by the IEEE's Electronics Packaging Society (EPS), ITherm 2020 will be held along with the 70th ECTC 2020. Joint registrations are available at a discounted rate.

May 26 – 29, 2020

Walt Disney World Swan & Dolphin Hotel

Orlando, FL, USA

Program Preview

In addition to paper presentations and vendor exhibits, ITherm 2020 will have panel discussions, keynote lectures by prominent speakers, invited tech talks, professional development courses, a student poster and networking session, invited exhibitor presentations, Richard Chu award presentation, and the art-in-science exhibition.

Technical Paper Presentations

ITherm 2020 will have peer-reviewed papers presented in over 40 sessions organized into the following tracks:

- Component-Level Thermal Management
- System-Level Thermal Management
- Mechanics & Reliability
- Emerging Technologies and Fundamentals

Tech Talk Sessions

- Transient Thermal Management
- Heterogeneous Integration
- Aerospace/Automotive/Telecom
- Innovation in Heat Exchangers
- AI in Thermal Management/Systems

Panel Sessions

- Thermal Challenges in Next-Generation Opto-Electronics
- Advances in Thermal Management: Machine Learning & Beyond
- Model-Based Design of Novel Electronic Components and Systems
- Thermomechanical Management of Advanced Mobile/Telecom, Wireless, and Computing Devices
- Two-Phase Liquid Cooling Systems

Research Workshop on Fundamentals of Two-Phase Flow

Keynote Speakers

The Future of 3D System Integration Technology: Keeping Cool While Turning up the Heat
Eric Beyne, *Imec*

Future of Work depends on Ethics in AI
Beena Ammanath, *Deloitte*

Aircraft Electrification Feasibility and Thermal Management Challenges
Charles Lents, *United Technologies Research Center*

Professional Development Courses

A set of 18 PDCs are being offered as a collaboration between the co-located ITherm and ECTC Conferences

Student Design Competition

ASME/K16 and IEEE/EPS are hosting an additive heat sink design competition with travel awards for qualifying teams.

ECTC/ITherm Diversity Panel

Heterogeneous Integration Roadmap

ITherm provides an opportunity for industrial and university participation in the form of financial support to ITherm 2020. All contributors will be given strong recognition both onsite and in the conference materials.

Join the ITherm LinkedIn Group
https://www.linkedin.com/groups/8650280

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